

Application No. 09/991,931

particular region of the one side, ~~formed on~~ the conductive member formed over the penetrating holes, a part of the adhesive material formed on internal wall surfaces forming the penetrating holes, so as not to stop up the penetrating holes.

70. (Amended) The method of manufacturing a substrate as defined in claim 66, wherein the substrate is either of an insulating film or of printed substrate.

71. (Amended) The method of manufacturing a substrate as defined in claim 67, wherein the substrate is either of an insulating film or of printed substrate.

#### REMARKS

Claims 53-73 are pending. By this Amendment, the specification is amended and claims 53, 70 and 71 are amended.

The attached Appendix includes marked-up copies of each rewritten paragraph (37 C.F.R. §1.121(b)(1)(iii)) and claim (37 C.F.R. §1.121(c)(1)(ii)).

#### **I. Specification Satisfies All Formal Requirements**

The Office Action objects to the specification for failure to include the continuing data as well as for confusion with respect to Figs. 8A and 8B. Attached hereto is the Continuing Application Transmittal which, at paragraph 5, amends the specification to include the continuation data. Also, attached hereto is a Response to Notice to File Corrected Application Papers With Formal Drawings indicating that Figs. 8A and 8B are the correct figures.

The specification has been amended at page 25, lines 17-22 to obviate the remaining objection.

#### **II. The Claims Satisfy All Formal Requirements**

The Office Action objects to claims 70 and 71 due to informalities. Claims 70 and 71 are amended to obviate this objection.

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**III. Double Patenting Rejection**

The Office Action rejects claims 53-65 under the judicially created doctrine of obviousness-type double patenting over claims 1, 2, 3, 7, 8, 10, 11, 17, 19 and 20 of U.S. Patent No. 6,097,610 and claims 66-73 under the judicially created doctrine of obviousness-type double patenting over claims 1, 3, 6, 8, 10, 11, 13 and 16 of U.S. Patent No. 6,340,606.

These rejections are obviated by the enclosed Terminal Disclaimer.

**IV. The Claims Define Patentable Subject Matter**

The Office Action rejects claims 53, 54, 56, 58 and 64 under 35 U.S.C. §102(e) over U.S. Patent No. 6,208,525 to Imasu et al. and claims 53 and 54 under 35 U.S.C. §102(e) over U.S. Patent No. 5,844,317 to Bertolet et al. These rejections are respectfully traversed.

Regarding claim 53, Imasu discloses a conductive member 15 formed inside a penetrating hole. In claim 53, the conductive member is formed over the penetrating holes. Bertolet discloses an adhesive material 190 stopping up a penetrating hole. In claim 53, a part of the adhesive material is formed so as not to stop up the penetrating holes.

**V. Conclusion**

In view of the foregoing, Applicant submits that this application is in condition for allowance. Favorable reconsideration and prompt allowance are earnestly solicited.

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Should the Examiner believe that anything further would be desirable in order to place this application in better condition for allowance, the Examiner is invited to contact Applicant's undersigned representative at the telephone number set forth below.

Respectfully submitted,

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Registration No. 27,075

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JAO:MB/nra

## Attachments:

Appendix  
Copy of Application Transmittal  
Copy of Response to Notice to File Corrected Application Papers  
with Formal Drawings  
Terminal Disclaimer

Date: DRAFT

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Please grant any extension  
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## APPENDIX

## Changes to Specification:

Page 25, lines 17-23:

In this way, after the penetrating holes 214a are formed, the conductive member 118 is formed on the substrate 214, to constitute two-layer substrate. For example, if the substrate 214 is of a thermoplastic substance, it can be softened by heating, and a conductive foil adhered without the use of adhesive, and by etching thereof a conductive member 218 can be formed. Alternatively, sputtering may equally be applied.

218  
118

## Changes to Claims:

53. (Amended) A substrate having penetrating holes formed therein, the substrate having a conductive member adhered on one side thereof by an adhesive material over a particular region of the one side including the penetrating holes, a part of the adhesive material is partially interposed in internal wall surfaces forming the penetrating holes.

70. (Amended) The method of manufacturing a substrate as defined in claim 66, wherein the substrate is either of an insulating film ~~and/or~~ of printed substrate.

71. (Amended) The method of manufacturing a substrate as defined in claim 67, wherein the substrate is either of an insulating film ~~and/or~~ of printed substrate.

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